

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LEILEI ZHANG	10/14/2013
RECEIVING PARTY DATA	
Name:	NVIDIA CORPORATION
Street Address:	2701 SAN TOMAS EXPRESSWAY
City:	SANTA CLARA
State/Country:	CALIFORNIA
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14053450
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Address Line 2:	SUITE 1500
Address Line 4:	HOUSTON, TEXAS 77056
ATTORNEY DOCKET NUMBER:	NVDA/SC-13-0049-US1
NAME OF SUBMITTER:	JOHN C. CAREY
Signature:	/John C. Carey/
Date:	10/15/2013
Total Attachments: 2 source=NVDA_SC-13-0049_US1_ASG#page1.tif source=NVDA_SC-13-0049_US1_ASG#page2.tif	

OP \$40.00 14053450

Attorney Docket No.: NVDA/SC-13-0049-US1

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Leilei ZHANG, residing at
1452 Dove Lane
Sunnyvale, California 94087

(hereinafter referred to as Assignor), has invented a certain invention entitled:

MICROELECTRONIC PACKAGE WITH STRESS TOLERANT SOLDER BUMP PATTERN

enclosed herewith or for which application for Letters Patent in the United States under Application No. _____, filed on _____, and

WHEREAS, **NVIDIA CORPORATION**, a Corporation of the State of Delaware having a place of business at 2701 San Tomas Expressway, Santa Clara, California 95050 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignor, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

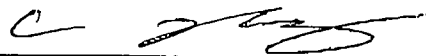
4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. I hereby authorize and request my attorneys, Patterson & Sheridan LLP, of 3040 Post Oak Blvd, Suite 1500, Houston Texas 77056, to insert above in parentheses (Application No. and Filing Date) the filing date and application number of said application when known.

Attorney Docket No.: NVDA/SC-13-0049-US1

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) Oct. 14, 2013



Leilei ZHANG